

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

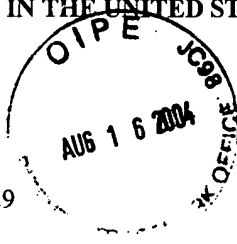
In re Application of

Ryosuke USUI, et al.

Serial No.: 10/813,629

Filed: March 31, 2004

For: SEMICONDUCTOR MODULE AND METHOD OF MANUFACTURING THE SAME



: Customer Number: 20277

: Confirmation Number: 3812

: Group Art Unit: 2811

: Examiner:

**REQUEST FOR CORRECTED FILING RECEIPT**

Mail Stop OFR  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Attached is a copy of the Filing Receipt received from the U.S. Patent and Trademark Office in the above-referenced application. It is noted that 1 of the 3 Foreign Priority information cited on the Official filing Receipt was omitted. Attached is a copy of the Declaration and Power of Attorney Document, which evidences that the omitted Foreign Priority information should be included and read:

**JP 2004-065243, filed on March 9, 2004.**

A total of 3 Foreign Applications should be cited on the Official Filing receipt as seen below:

**JP2004-065243, filed on March 9, 2004. (Omitted)**

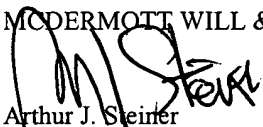
**JP2003-093324, filed on March 31, 2003.**

**JP2004-086770, filed March 24, 2004.**

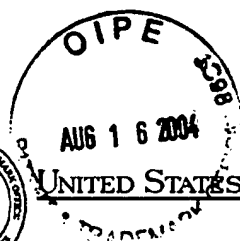
It is requested that a corrected filing receipt be issued.

Respectfully submitted,

MCDERMOTT WILL & EMERY LLP

  
Arthur J. Steiner  
Registration No. 26,106

600 13<sup>th</sup> Street, N.W.  
Washington, DC 20005-3096  
202.756.8000 AJS:gav  
Facsimile: 202.756.8087  
**Date: August 16, 2004**



## UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
 United States Patent and Trademark Office  
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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/813,629	03/31/2004	2811	0.00	65933-084	15	22	5

CONFIRMATION NO. 3812

MCDERMOTT, WILL & EMERY  
 600 13th Street, N.W.  
 Washington, DC 20005-3096

## FILING RECEIPT



\*OC000000012955728\*

Date Mailed: 06/15/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Ryosuke Usui, Residence Not Provided;  
 Hideki Mizuhara, Residence Not Provided;  
 Takeshi Nakamura, Residence Not Provided;

## Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 2003-093324 03/31/2003  
 JAPAN 2004-086770 03/24/2004

If Required, Foreign Filing License Granted: 06/15/2004

Projected Publication Date: To Be Determined - pending completion of Missing Parts

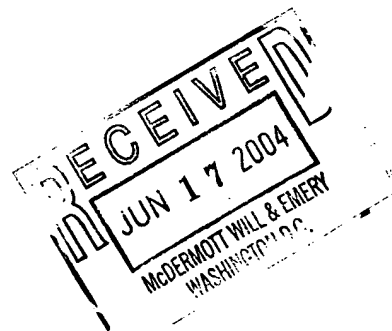
Non-Publication Request: No

Early Publication Request: No

## Title

Semiconductor module and method of manufacturing the same

## Preliminary Class



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**LICENSE FOR FOREIGN FILING UNDER  
Title 35, United States Code, Section 184  
Title 37, Code of Federal Regulations, 5.11 & 5.15**

**GRANTED**

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Docket No.:

## **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR MODULE AND METHOD OF MANUFACTURING THE SAME, the specification of which

☐ is attached hereto.

☒ was filed on March 31, 2004 as Application Serial No. (if applicable).

and was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

### **Prior Foreign Applications(s):**

Number	Country	Day/Month/Year filed	Priority Claimed
JP2003-093324	Japan	31/March/2003	Yes
JP2004-065243	Japan	09/March/2004	Yes
JP2004-086770	Japan	24/March/2004	Yes

I hereby claim the benefit under 35 USC §119(e) of any United States provisional application(s) listed below.

### **Prior Provisional Application(s):**

Application Number	Filing Date
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I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

### **Prior U.S. Application(s):**

Serial No.	Filing Date	Status: Patented, Pending, Abandoned
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Steven W. Allis, Reg. No. 50,532; Stephen A. Becker, Reg. No. 26,527; John G. Bisbikis, Reg. No. 37,095; Daniel Bucca, Reg. No. 42,368; Kenneth L. Cage, Reg. No. 26,151; Jennifer Chen, Reg. No. 42,404; Bernard P. Codd, Reg. No. 46,429; Lawrence T. Cullen, Reg. No. 44,489; Paul Devinsky, Reg. No. 28,553; Margaret M. Duncan, Reg. No. 30,879; Shamita De. Etienne-Cummings, Reg. No. 46,072; Ramyar M. Farid, Reg. No. 46,692; Brian E. Ferguson, Reg. No. 36,801; Michael E. Fogarty, Reg. No. 36,139; John R. Fuisz, Reg. No. 37,327; Willem F. Gadiano, Reg. No. 37,136; Keith E. George, Reg. No. 34,111; John A. Hankins, Reg. No. 32,029; Eric J. Kraus, Reg. No. 36,190; Catherine Krupka, Reg. No. 46,227; Jack Q. Lever, Reg. No. 28,149; Raphael V. Lupo, Reg. No. 28,363; Burman Y. Mathis III, Reg. No. 44,907; Michael A. Messina, Reg. No. 33,424; Dawn L. Palmer, Reg. No. 41,238; Joseph H. Paquin, Jr., Reg. No. 31,647; Scott D. Paul, Reg. No. 42,984; William D. Pegg, Reg. No. 42,988; Robert L. Price, Reg. No. 22,685; Gene Z. Robinson, Reg. No. 33,351; Brian K. Seidleck, Reg. No. 51,321; Joy Ann G. Serauskas, Reg. No. 27,952; David A. Spenard, Reg. No. 37,449; Arthur J. Steiner, Reg. No. 26,106; David L. Stewart, Reg. No. 37,578; Wesley Strickland, Reg. No. 44,363; Michael D. Switzer, Reg. No. 39,552; David M. Tennant, Reg. No. 48,362; Judith L. Toffenetti, Reg. No. 39,048; Daniel S. Trainor, Reg. No. 43,959; Kelli N. Watson, Reg. No. 47,170; Cameron K. Weiffenbach, Reg. No. 44,488; Aaron Weisstuch, Reg. No. 41,557; Edward J. Wise, Reg. No. 34,523; Jeffrey A. Woller, Reg. No. 48,041; Alexander V. Yampolsky, Reg. No. 36,324; Robert W. Zelnick, Reg. No. 36,976; and Wei-Chen Chen, admitted under 37 CFR 10.9(b) all of

McDERMOTT, WILL & EMERY  
600 13<sup>th</sup> Street, N.W.  
Washington, DC 20005-3096

Direct Telephone Calls to: Telephone 202-756-8000

with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.

Full name of sole or first inventor: Ryosuke Usui

Inventor's signature: *Ryosuke Usui*

Date: *16/June/2004*

Residence: Ichinomiya-shi, Aichi, Japan

Citizenship: Japan

Post Office Address: 2-4-17-605, Showa, Ichinomiya-shi, Aichi, 491-0917 Japan

Full name of second inventor: Hideki Mizuhara

Inventor's signature: *Hideki Mizuhara*

Date: *16/June/2004*

Residence: Bisai-shi, Aichi, Japan

Citizenship: Japan

Post Office Address: 34-1, Aza-Yuukuno, Higashiitsushiro, Bisai-shi, Aichi, 494-0008 Japan

Full name of third inventor: Takeshi Nakamura

Inventor's signature: *Takeshi Nakamura*

Date: *16/June/2004*

Residence: Sawa-gun, Gunma, Japan

Citizenship: Japan

Post Office Address: 5947-22, Higashiobokata, Azuma-mura, Sawa-gun, Gunma 379-2223 Japan